CLAIMS

1. Use of a heat-transfer fluid comprising at least one diester of at least one C_2-C_9 aliphatic diol with at least one linear or branched C_2-C_7 aliphatic monocarboxylic acid, for cooling an electronic component with an indirect liquid cooling system.

2. The use according to claim 1, wherein in said heat-transfer fluid said C_2-C_9 aliphatic diol of said diester is selected from the group consisting of: ethylene glycol, 1,2-propanediol, 1,3- propanediol, 1,4-butanediol, 1,3-butanediol, di-ethylene glycol, tri-ethylene glycol, di-propylene glycol, neopentyl glycol, 2-methyl-1,3-propanediol, 1,5-pentanediol, 1,6-hexanediol, 3-metyl-1,5-pentanediol, 2-butyl-2-ethyl-1,3-propanediol, 2,2,4-trimethyl-1,3-pentanediol and mixtures thereof.

3. The use according to claim 1 or 2, wherein in said heat-transfer fluid said aliphatic diol of the diester is a C_3-C_6 aliphatic diolor

said aliphatic diol of said diester is a C_3-C_5 aliphatic diol.

4. The use according to any one of claims from 1 to 3, wherein in said heat-transfer fluid said monocarboxylic acid of said diester is a C_3-C_5 aliphatic monocarboxylic acid or

said monocarboxylic acid of said diester is a C_5-C_7 aliphatic monocarboxylic acid.

5. The use according to any one of claims from 1 to 4, wherein in said heat-transfer fluid said diester is selected from the group consisting of: neopentyl glycol divalerate, 1,2-propanediyl divalerate, 1,3-propanediyl divalerate, 2-methyl-1,3-propanediyl divalerate and mixtures thereof.

6. The use according to any one of claims from 1 to 5, wherein said indirect liquid cooling system comprises:

a liquid cooling loop apt to circulate said heat-transfer fluid;

a pump apt to pump said heat-transfer fluid throughout said liquid cooling loop;

a heat exchanger apt to cool said heat-transfer fluid; and

optionally, a reservoir apt to contain said heat-transfer fluid.

7. The use according to any one of claims from 1 to 6, wherein said electronic component is selected from the group consisting of: a microprocessor, a

semiconductor wafer, a power control semiconductor, an electrochemical cell, an electrical distribution switch gear, a power transformer, a circuit board, a multi-chip module, an hard disk, a central processing unit, a packaged or unpackaged semiconductor device, a fuel cell, a laser, and a semiconductor integrated circuit.

8. The use according to any one of claims from 1 to 7, wherein said electronic component is mounted in an electronic device.

9. The use according to claim 8, wherein said electronic device is selected from the group consisting of: a computer, a server, a server farm, a telecommunication centre, and a datacentre.

10. A method for cooling an electronic component with an indirect liquid cooling system, wherein said liquid cooling system comprises a heat-transfer fluid comprising at least one diester of at least one C_2-C_9 aliphatic diol with at least one linear or branched C_2-C_7 aliphatic monocarboxylic acid.

11. The method according to claim 10, wherein said method comprises the step of: transferring heat from said electronic component to said heat-transfer fluid.

12. The method according to claim 10 or 11, wherein said heat-transfer fluid is an heat-transfer fluid according to any claims from 1 to 5.

13. An electronic device comprising:

at least one electronic component; and

at least one indirect liquid cooling system apt to cool said electronic component and comprising at least one heat-transfer fluid comprising at least one diester of a C_2-C_9 aliphatic diol with at least one linear or branched C_2-C_7 aliphatic monocarboxylic acid.

14. The electronic device according to claim 13, wherein said heat-transfer fluid is an heat-transfer fluid according to any claims from 1 to 5.

15. A heat transfer fluid for cooling an electronic component, comprising at least one diester of a C_2-C_9 aliphatic diol with at least one linear or branched C_2-C_7 aliphatic monocarboxylic acid and at least one an additive selected from the group consisting of: an antioxidant, a pour-point-depressant additive, an antifoam, an anticorrosion agent, a viscosity modifier, a wear-resistance and/or extreme-pressure additive, a friction modifier, a detergent, a dispersant, and mixtures thereof.